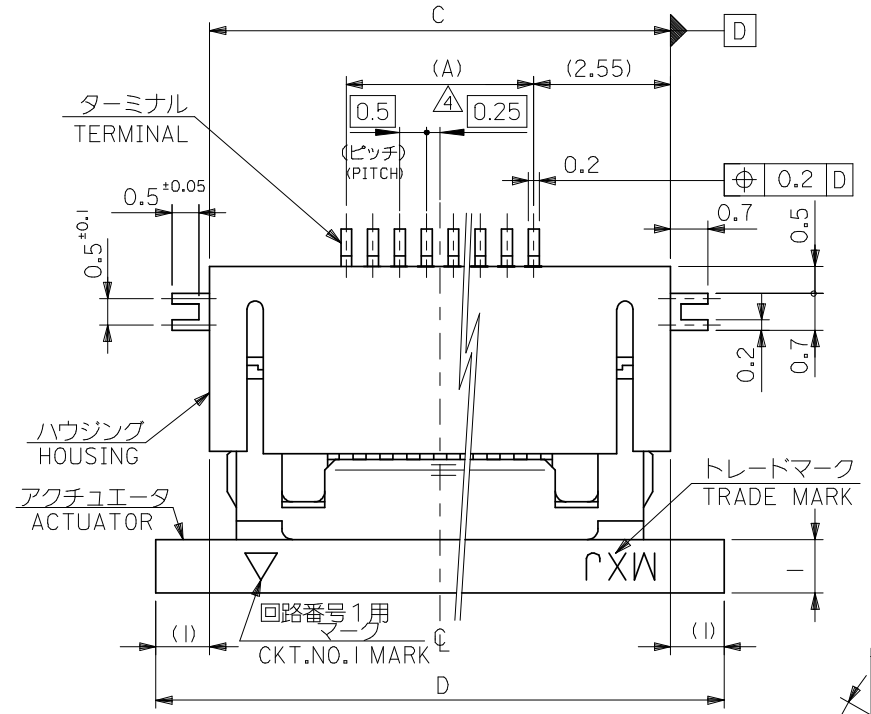
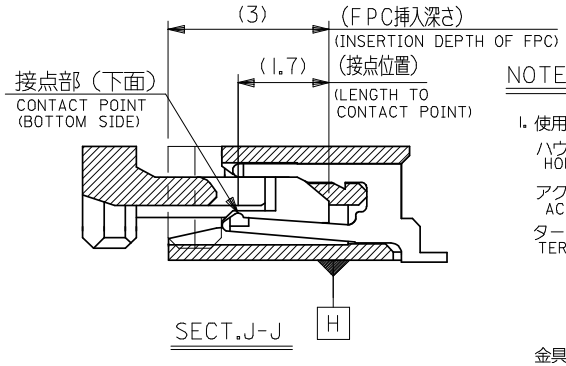
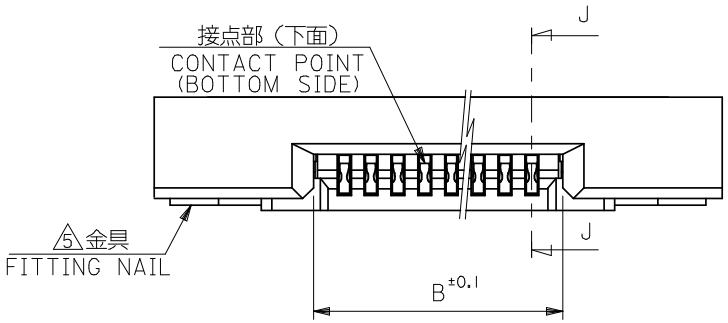
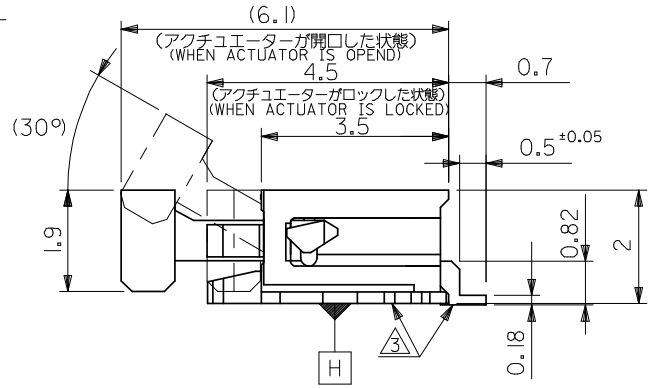








NOTES

1. 使用材料：MATERIAL
   - ハウジング HOUSING ：46ナイロン、UL94V-0 / 46NYLON
   - アクチュエータ ACTUATOR ：PPS、UL94V-0
   - ターミナル TERMINAL ：リン青銅（t＝0．2） / :PHOSPHOR BRONZE / :錫ビスマスメッキ 1．0マイクロメートル以上 / :TIN-BISMUTH 1.0 MICROMETER MINIMUM / :ニッケル下地 1．0マイクロメートル以上 / :NICKEL(UNDER PLATING) 1.0 MICROMETER MINIMUM
   - 金具 FITTING NAIL ：リン青銅（t＝0．2） / :PHOSPHOR BRONZE / :錫メッキ 1．0マイクロメートル以上 / :TIN 1.0 MICROMETER MINIMUM / :ニッケル下地 1．0マイクロメートル以上 / :NICKEL(UNDER PLATING) 1.0 MICROMETER MINIMUM
2. エンボステープ梱包時は、アクチュエータがロックした状態とする。
   IN THE PACKAGE,ACTUATOR OF PART NO.52437-**26 SHOULD BE LOCKED.
3. ソルダーテール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 H に対し上方向 0.1 MAX. ，下方向 0.15MAX. とする。
   MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM H
   UPPER DIRECTION: 0.1 MAX. , LOWER DIRECTION: 0.15MAX.
4. 偶数極に適用。
   APPLY FOR EVEN CIRCUIT.
5. パターンはくり止め用金具。
   FITTING NAIL FOR PREVENTION OF PEELING OF P.C.B. PATTERN.
6. R0．3は、FPCの導体部にかからないこと。
   R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.
7. 本製品は 52437-**27の鉛フリー品である。
   THIS PRODUCT IS LEAD FREE OF 52437-**27.
8. ソルダーテールの平坦度は、0.1 MAXIMUM とする．
   SOLDER TAIL COPLANARITY IS 0.1 MAXIMUM.

REVISED	EC NO:	DESCRIPTION	REV
	J2008-4048		C
DRWN:	MNABEI 2008/06/13		
CH'KD:	THARUYAMA 2008/06/16		
APPR:	NUKITA 2008/06/16		

GENERAL TOLERANCES (UNLESS SPECIFIED)

10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR	±3 °

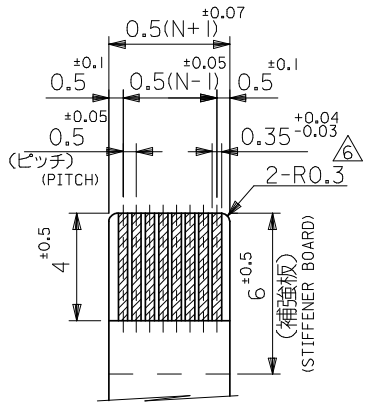
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	MM ONLY
SCALE	---
DESIGN UNITS	METRIC
	THIRD ANGLE PROJECTION
DRAWN BY	YSAKIYAM
DATE	'04/01/08
CHECKED BY	MSASAO
DATE	'04/01/08
APPROVED BY	MSASAO
DATE	'04/01/08
MATERIAL NO.	SEE SHEET 2
DOCUMENT NO.	SD-52437-017
SHEET NO.	1 OF 2
SIZE	A3

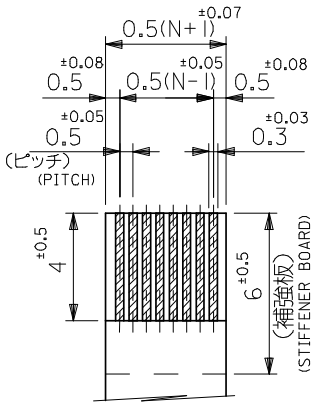
52437-**26 MODEL NO.

TITLE: 0.5 FPC CONN ZIF SMT RA BOTTOM CONTACT -LEAD FREE-

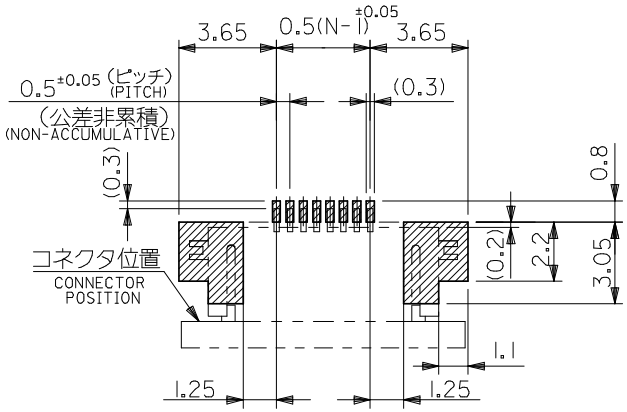
molex MOLEX INCORPORATED



適合ＦＰＣ推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION.
(仕上がり厚さ：$0.3^{\pm0.05}$)
(THICKNESS:$0.3^{\pm0.05}$)



適合ＦＦＣ推奨寸法
APPLICABLE FFC
RECOMMENDED DIMENSION.
(仕上がり厚さ：$0.3^{\pm0.05}$)
(THICKNESS:$0.3^{\pm0.05}$)



参考基板レイアウト
（マウント面）
RECOMMENDED P.C.BOARD
PATTERN DIMENSION (REF.)
(MOUNTING SIDE)

ＦＰＣについて：
打抜き方向は導体側から補強板側を推奨致します。
補強フィルム材質はポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION :
FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED MATERIAL:
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

D	C	B	(A)	EMBOSSED TAPE ORDER No. オーダー番号		MATERIAL NO.	極数 CKT.
21.6	19.6	15.65	14.5	52437-3072		52437-3026	30
21.1	19.1	15.15	14.0	-2972		-2926	29
20.6	18.6	14.65	13.5	-2872		-2826	28
20.1	18.1	14.15	13.0	-2772		-2726	27
19.6	17.6	13.65	12.5	-2672		-2626	26
19.1	17.1	13.15	12.0	-2572		-2526	25
18.6	16.6	12.65	11.5	-2472		-2426	24
18.1	16.1	12.15	11.0	-2372		-2326	23
17.6	15.6	11.65	10.5	-2272		-2226	22
17.1	15.1	11.15	10.0	-2172		-2126	21
16.6	14.6	10.65	9.5	-2072		-2026	20
16.1	14.1	10.15	9.0	-1972		-1926	19
15.6	13.6	9.65	8.5	-1872		-1826	18
15.1	13.1	9.15	8.0	-1772		-1726	17
14.6	12.6	8.65	7.5	-1672		-1626	16
14.1	12.1	8.15	7.0	-1572		-1526	15
13.6	11.6	7.65	6.5	-1472		-1426	14
13.1	11.1	7.15	6.0	-1372		-1326	13
12.6	10.6	6.65	5.5	-1272		-1226	12
12.1	10.1	6.15	5.0	-1172		-1126	11
11.6	9.6	5.65	4.5	-1072		-1026	10
11.1	9.1	5.15	4.0	-0972		-0926	9
10.6	8.6	4.65	3.5	-0872		-0826	8
10.1	8.1	4.15	3.0	-0772		-0726	7
9.6	7.6	3.65	2.5	52437-0672		52437-0626	6

REVISED
EC NO: J2008-4048 2008/06/13
DRWN:MNABEI 2008/06/16
CH'KD: APPR:NUKITA 2008/06/16
DESCRIPTION
REV
C

GENERAL TOLERANCES (UNLESS SPECIFIED)

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DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: ---
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: YSAKIYAM DATE: '04/01/08
CHECKED BY: MSASAO DATE: '04/01/08
APPROVED BY: MSASAO DATE: '04/01/08
MATERIAL NO.: SEE TABLE

TITLE: 0.5 FPC CONN ZIF SMT RA BOTTOM CONTACT -LEAD FREE-

MOLEX INCORPORATED

DOCUMENT NO.: SD-52437-017
SHEET NO.: 2 OF 2
SIZE: A3